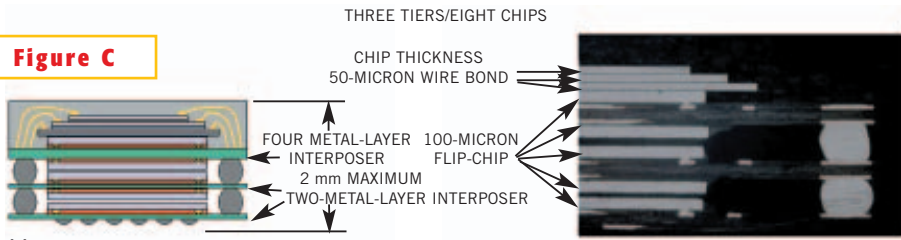


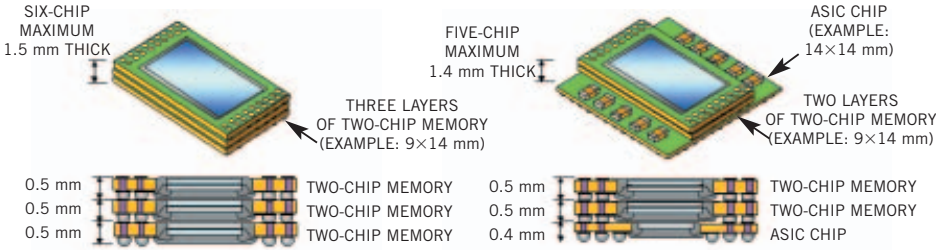
**Figure C**



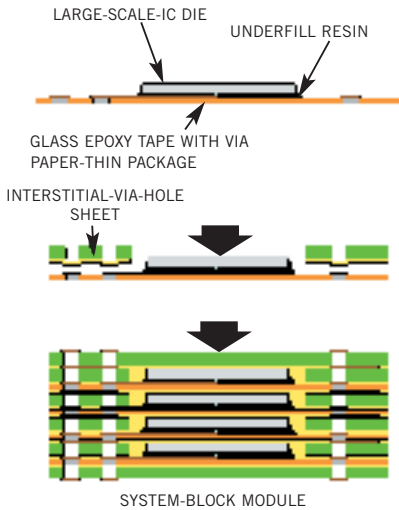
(a)

LARGE-CAPACITY COMBO MEMORY  
(FOUR TO SIX MEMORY CHIPS)

SYSTEM LARGE-SCALE IC  
(ASIC CHIP+FOUR MEMORY CHIPS)



(b)



(c)

Fujitsu (a), Sharp (b), and Toshiba (c) are working on rapidly adaptable stacked-chip arrangements.